

Operational Amplifiers

Low Current Consumption Input/Output Full Swing Operational Amplifier



BD12730G

● **General Description**

BD12730 is a low supply voltage single operational amplifier that operates from 1.8V to 5V. Its input and output full swing, from ground to power supply level, provides wide dynamic range. This amplifier features low noise and high phase margin which makes it ideal for audio applications, battery management and other applications.

● **Features**

- Low operating supply voltage
- Input/Output Full Swing
- Low input offset voltage
- Low Power Consumption
- High Phase margin
- Low Input Referred Noise Voltage

● **Application**

- Audio application
- Buttery management
- General Purpose

● **Simplified schematic**

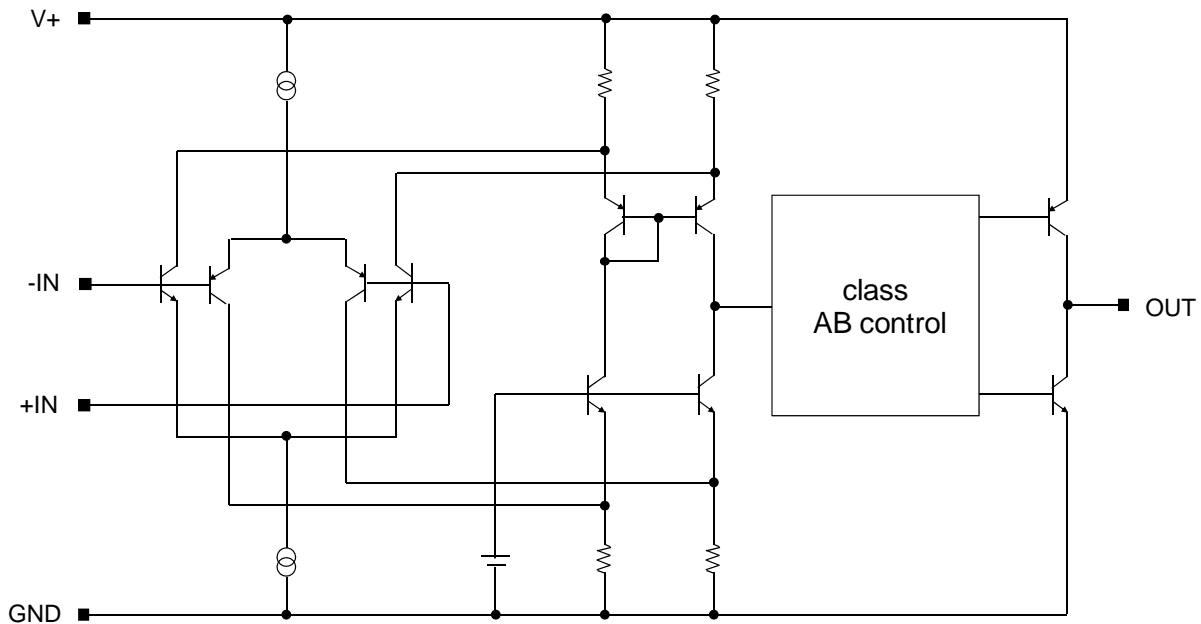


Figure 1. Simplified schematic

● **Key Specifications**

- Low Operating Supply Voltage (Single Supply) +1.8V to +5.0V
- Wide Temperature Range: -40°C to +85°C
- Low Input Offset Voltage 5mV (Max.)
- Slew Rate 0.4V/μs (Typ.)
- Low Input Referred Noise Voltage 10 nV/√Hz (Typ.)
- Adequate Phase Margin 75°(Typ.)

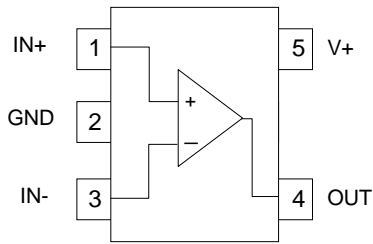
● **Package**
SSOP5

W(Typ.) xD(Typ.) xH(Max.)
2.90mm x 2.80mm x 1.25mm

○Product structure : Silicon monolithic integrated circuit ○This product is not designed to be protected against radioactive rays.

●Pin Configuration

SSOP5



Pin No.	Symbol
1	IN+
2	GND
3	IN-
4	OUT
5	V+

●Ordering Information

B D 1 2 7 3 0 G

- T R

Part Number
BD12730

Package
G: SSOP5

Packaging and forming specification
TR: Embossed tape and reel
(SSOP5)

●Line-up

Topr	Package		Operable Part Number
-40°C to +85°C	SSOP5	Reel of 3000	BD12730G-TR

●Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V+	+7.0	V
Power dissipation	Pd	675 ^{*1*2}	mW
Differential Input Voltage ^{*3}	Vid	±1.0	V
Input Common-mode Voltage Range	Vicm	GND to V+	V
Operating Supply Voltage	Vopr	+1.8 to +5.0	V
Operating Temperature	Topr	-40 to +85	°C
Storage Temperature	Tstg	-55 to +150	°C
Maximum Junction Temperature	Tjmax	+150	°C

Note: Absolute maximum rating of each item indicates the condition which must not be exceeded.
Application of voltage in excess of absolute maximum rating or usage out of absolute maximum rated temperature environment may cause deterioration of characteristics.

*1 When used at temperature above Ta=25°C, reduce by 5.4mW/°C.

*2 Mounted on a FR4 glass epoxy PCB (70mm×70mm×1.6mm).

*3 Differential input voltage is the voltage difference between inverting input and non-inverting input. Input terminal voltage is set to more than GND.

●Electrical Characteristics:

OBD12730G (Unless otherwise specified $V_{+}=+5V$, $GND=0V$, $T_a=25^{\circ}C$)

Parameter	Symbol	Limits			Unit	Condition
		Min.	Typ.	Max.		
Operating Current	ICC	-	320	550	μA	$R_L=\infty$, $V_{IN}=2.5V$
Input Offset Voltage ^{*4}	Vio	-	1	5	mV	-
Input Bias Current ^{*4}	Ib	-	50	250	nA	-
Input Offset Current ^{*4}	Iio	-	5	100	nA	-
Voltage Gain	Av	60	85	-	dB	$R_L=2k\Omega$
Common-mode Rejection Ratio	CMRR	55	70	-	dB	-
Supply Voltage Rejection Ratio	PSRR	70	85	-	dB	-
Maximum Output Voltage 1	VOH1	4.9	4.95	-	V	$R_L=20k\Omega$
	VOL1	-	0.05	0.1	V	
Maximum Output Voltage 2	VOH2	4.75	4.85	-	V	$R_L=2k\Omega$
	VOL2	-	0.15	0.25	V	
Output Source Current ^{*6}	Isource	-	12	-	mA	OUT=0V
Output Sink Current ^{*6}	Isink	-	5	-	mA	OUT=5V
Input Common-mode Voltage Range	Vicm	0	-	5	V	CMRR>55dB
Gain Bandwidth Product	GBW	-	1	-	MHz	$f=10kHz$
Unity Gain Bandwidth	f_T	-	1	-	MHz	$R_L=2k\Omega$
Phase margin	θ	-	75	-	deg	$R_L=2k\Omega$
Input Referred Noise Voltage	Vn	-	10	-	nV/\sqrt{Hz}	$f=1kHz$
		-	0.7	-	μV_{rms}	$R_S=100\Omega$ DIN-AUDIO
Slew Rate	SR	-	0.4	-	V/ μS	$R_L=2k\Omega$

*4 Absolute value.

Description of electrical characteristics

Described here are the terms of electric characteristics used in this datasheet. Items and symbols used are also shown. Note that item name, symbol and their meaning may differ from those on other manufacturer's document or general documents.

1. Absolute maximum ratings

Absolute maximum rating items indicate the condition which must not be exceeded. Application of voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

1.1 Supply Voltage (V+/GND)

Indicates the maximum voltage that can be applied between the positive power supply terminal and negative power supply terminal without deterioration or destruction of characteristics of internal circuit.

1.2 Differential Input Voltage (Vid)

Indicates the maximum voltage that can be applied between non-inverting terminal and inverting terminal without deterioration and destruction of characteristics of IC.

1.3 Input Common-mode Voltage Range (Vicm)

Indicates the maximum voltage that can be applied to the non-inverting terminal and inverting terminal without deterioration or destruction of characteristics. Input common-mode voltage range of the absolute maximum ratings does not assure normal operation of IC. When normal Operation of IC is desired, the input common-mode voltage of characteristics item must be followed.

1.4 Power dissipation (Pd)

Indicates the power that can be consumed by the IC when mounted on a specific board at ambient temperature 25°C (normal temperature). As for the packaged product, Pd is determined by the temperature that can be permitted by the IC in the package (maximum junction temperature) and the thermal resistance of the package

2. Electrical characteristics

2.1 Input offset voltage (Vio)

Indicates the voltage difference between non-inverting terminal and inverting terminal. It can be translated into the input voltage difference required for setting the output voltage to 0 V.

2.2 Input offset current (Iio)

Indicates the difference of input bias current between non-inverting terminal and inverting terminal.

2.3 Input bias current (Ib)

Indicates the current that flows into or out of the input terminal. It is defined by the average of input bias currents at non-inverting and inverting terminals.

2.4 Input Common Mode Voltage Range (Vicm)

Indicates the input voltage range where IC operates normally.

2.5 Maximum Output Voltage (High/Low Level Output Voltage) (VOH/VOL)

Indicates the voltage range that the IC can output under specified load condition. It is typically divided into high-level output voltage and low-level output voltage. High-level output voltage indicates the upper limit of output voltage. Low-level output voltage indicates the lower limit.

2.6 Voltage Gain (Av)

Indicates the amplification rate (gain) of the output voltage against the voltage difference between the non-inverting and inverting terminals. It is normally the amplification rate (gain) with reference to DC voltage.

$$A_v = (\text{Output voltage fluctuation}) / (\text{Input offset fluctuation})$$

2.7 Operating current (ICC)

Indicates the current that flows within the IC under specified no-load conditions.

2.8 Unity Gain Bandwidth (f_T)

Indicates the frequency where the voltage gain of Op-Amp is 1.

2.9 Phase Margin (θ)

Indicates the margin of phase from 180 degree phase lag at unity gain frequency.

2.10 Common Mode rejection ratio (CMRR)

Indicates the ratio of fluctuation of input offset voltage when the input common-mode voltage is changed. It is normally the fluctuation of DC.

$$CMR = (\text{Change of Input common-mode voltage}) / (\text{Input offset fluctuation})$$

2.11 Supply Voltage Rejection Ratio (PSRR)

Indicates the ratio of fluctuation of input offset voltage when supply voltage is changed. It is normally the fluctuation of DC.

$$PSRR = (\text{Change of power supply voltage}) / (\text{Input offset fluctuation})$$

2.12 Equivalent Input Noise Voltage (Vn)

Indicates a noise voltage generated inside the operational amplifier reflected back to an ideal voltage source connected in series with the input terminal.

2.13 Slew rate (SR)

Indicates the ratio of the change in output voltage with time when a step input signal is applied.

2.14 Output source current/ output sink current (I_{source} / I_{sink})

The maximum current that can be output under specific output conditions, it is divided into output source current and output sink current. The output source current indicates the current flowing out of the IC, and the output sink current the current flowing into the IC.

2.15 Gain Band Width (GBW)

Indicates to multiply by the frequency and the gain where the voltage gain decreases 6dB/octave.

● Typical Performance Curves
 OBD12730G

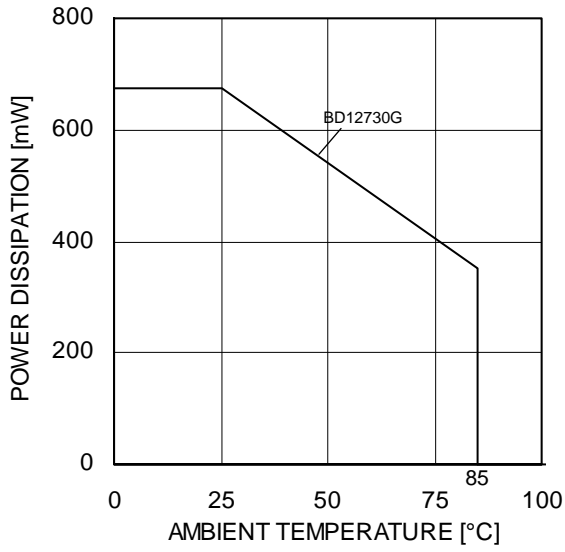


Figure 2.
 Derating curve

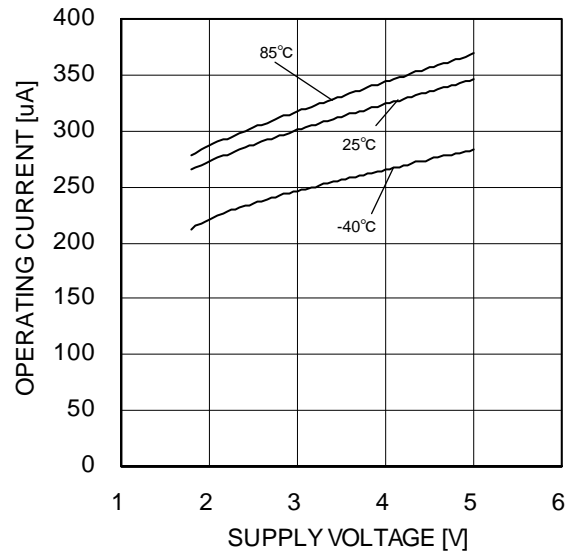


Figure 3.
 Operating Current - Supply Voltage

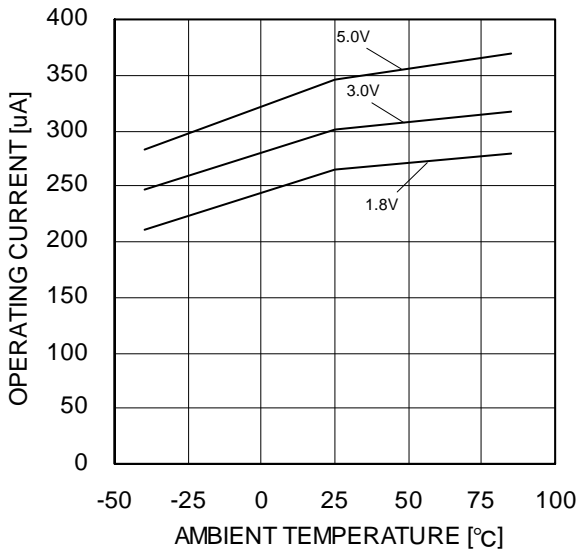


Figure 4.
 Operating Current - Ambient Temperature

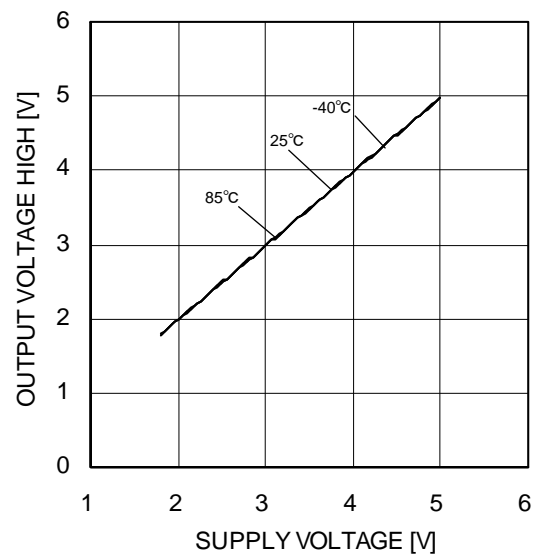


Figure 5.
 Output Voltage High - Supply Voltage
 (RL=20kΩ)

(*)The data above is measurement value of typical sample, it is not guaranteed.

● Typical Performance Curves (Reference data) – Continued
OBD12730G

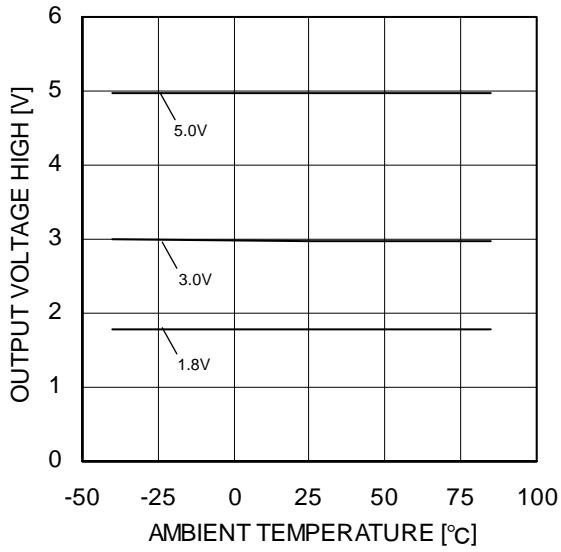


Figure 6.
 Output Voltage High - Ambient Temperature
 (RL=20kΩ)

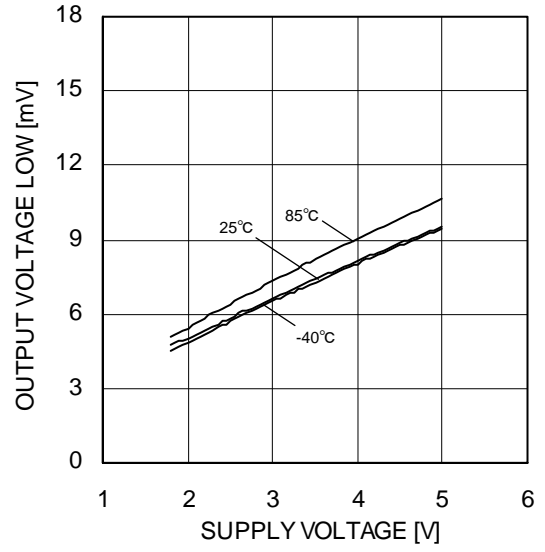


Figure 7.
 Output Voltage Low - Supply Voltage
 (RL=20kΩ)

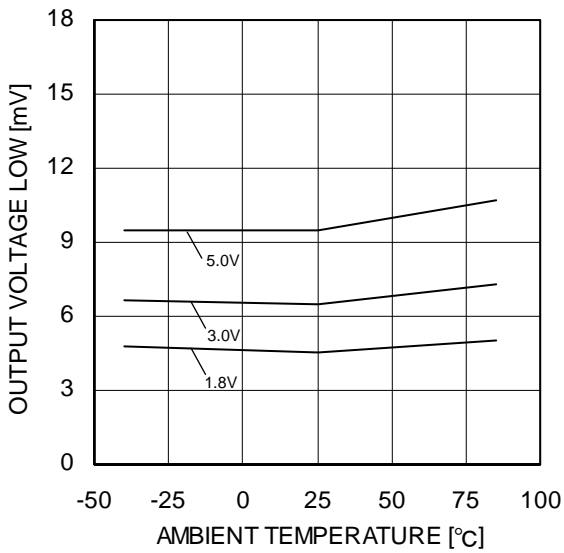


Figure 8.
 Output Voltage Low - Ambient Temperature
 (RL=20kΩ)

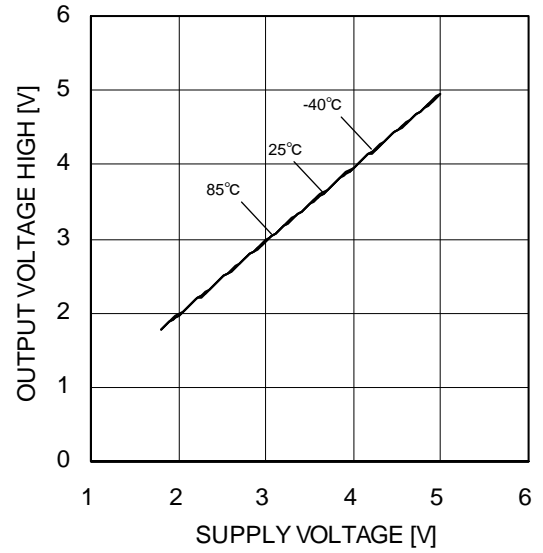


Figure 9.
 Output Voltage High - Supply Voltage
 (RL=2kΩ)

(*)The data above is measurement value of typical sample, it is not guaranteed.

● Typical Performance Curves (Reference data) – Continued
OBD12730G

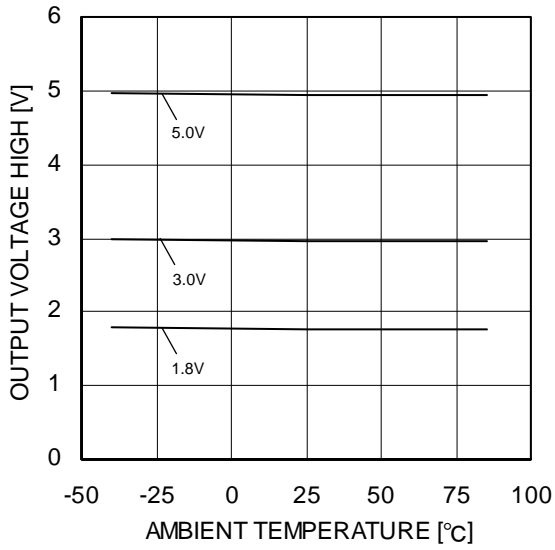


Figure 10.
 Output Voltage High - Ambient Temperature
 (RL=2kΩ)

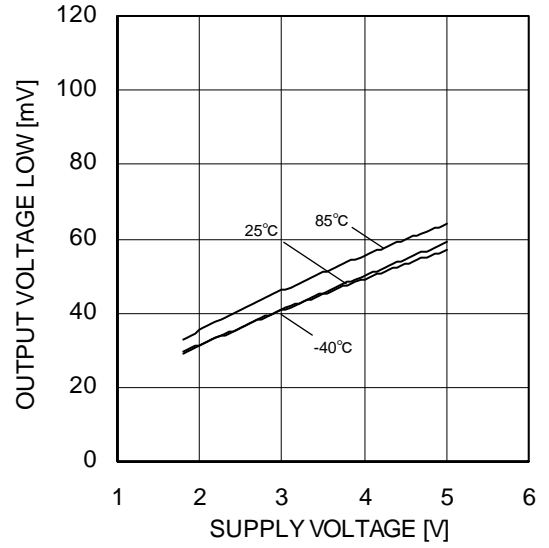


Figure 11.
 Output Voltage Low - Supply Voltage
 (RL=2kΩ)

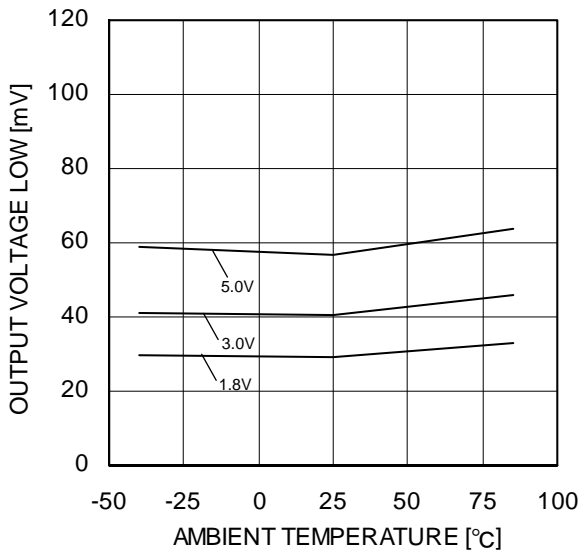


Figure 12.
 Output Voltage Low - Ambient Temperature
 (RL=2kΩ)

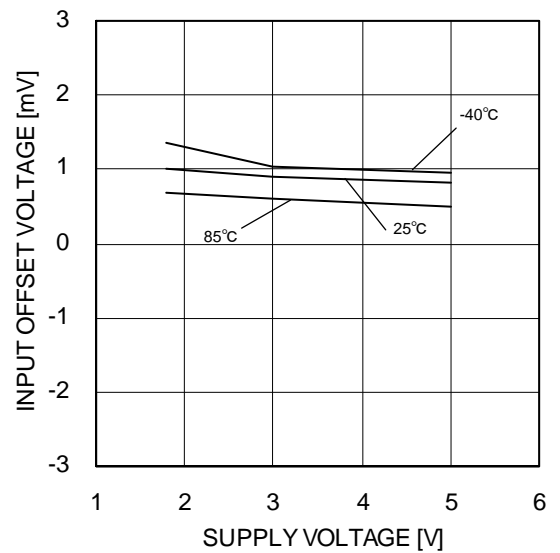


Figure 13.
 Input Offset Voltage - Supply Voltage

(*)The data above is measurement value of typical sample, it is not guaranteed.

● Typical Performance Curves (Reference data) – Continued
OBD12730G

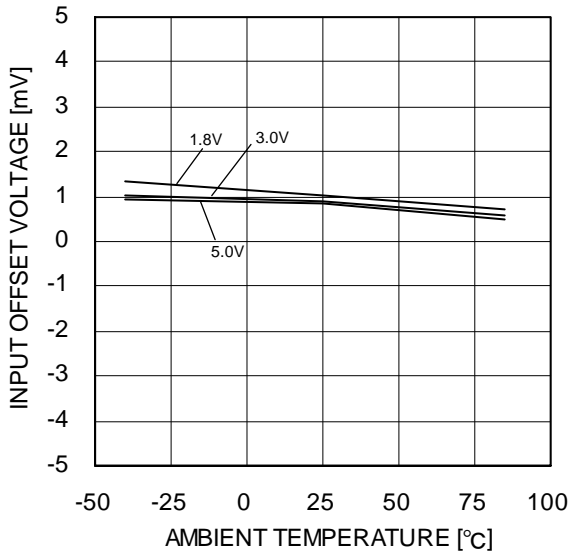


Figure 14.
 Input Offset Voltage - Ambient Temperature

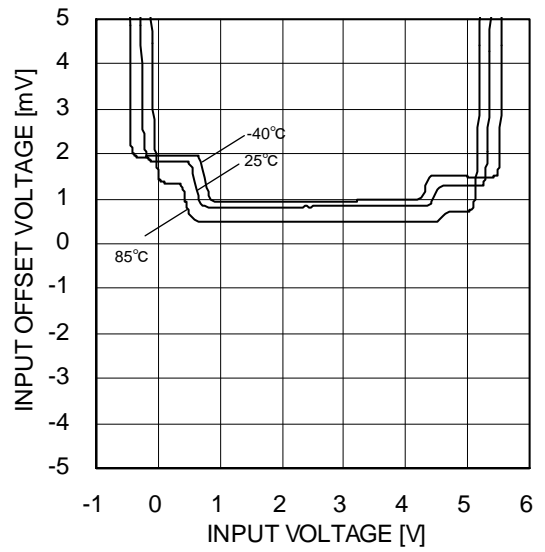


Figure 15.
 Input Common Mode Voltage Range
 ($V_{+}=5V$)

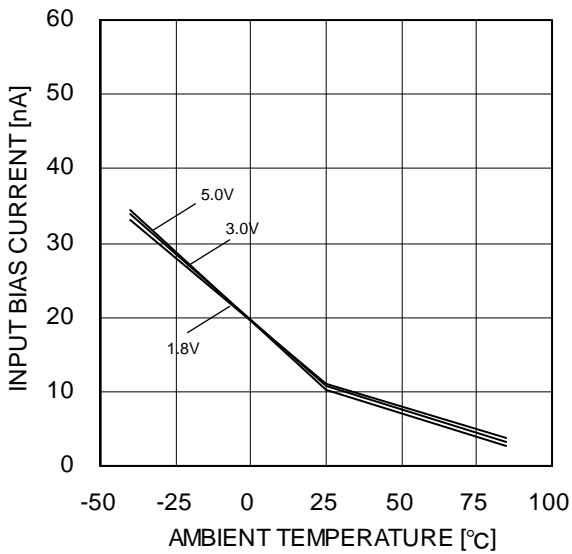


Figure 16.
 Input Bias Current - Ambient Temperature

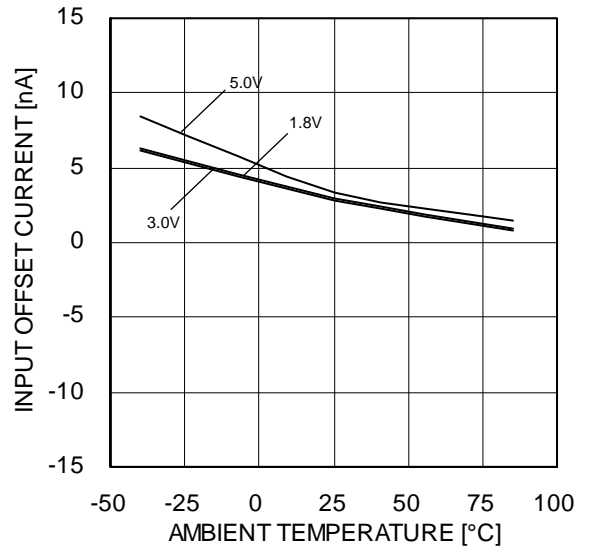


Figure 17.
 Input Offset Current - Ambient Temperature

(*)The data above is measurement value of typical sample, it is not guaranteed.

● Typical Performance Curves (Reference data) – Continued
OBD12730G

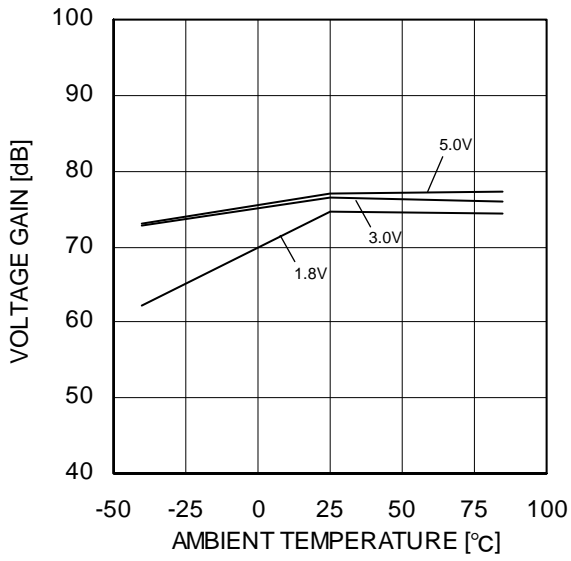


Figure 18.
 Voltage Gain - Ambient Temperature
 (RL=2kΩ)

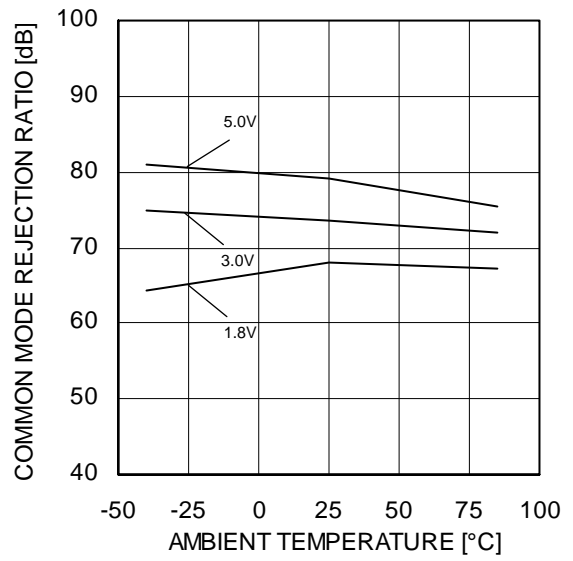


Figure 19.
 Common Mode Rejection Ratio - Ambient Temperature

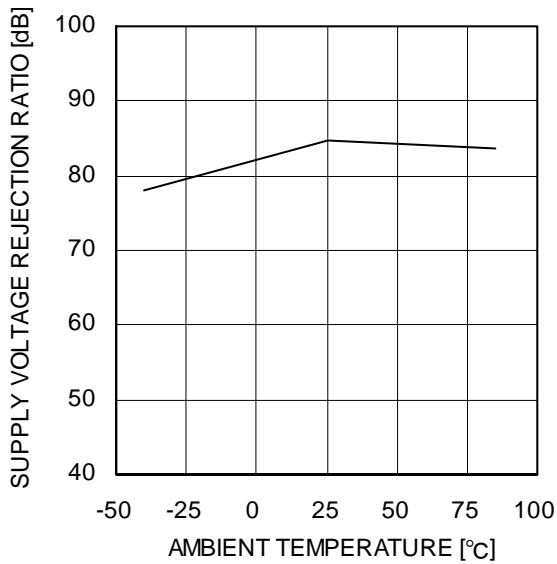


Figure 20.
 Supply Voltage Rejection Ratio - Ambient Temperature
 (V+=1.8 to 5.0V)

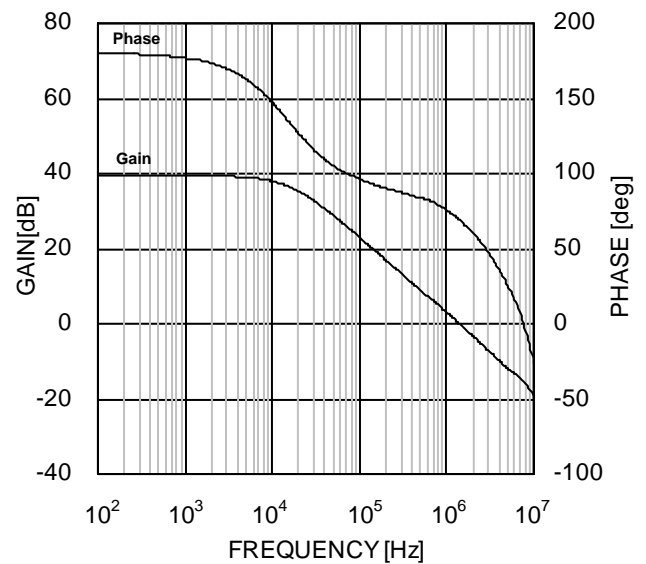


Figure 21.
 Voltage Gain · Phase - Frequency
 (V+=5V, RL=2kΩ, Ta=25°C)

(*)The data above is measurement value of typical sample, it is not guaranteed.

● Typical Performance Curves (Reference data) – Continued
OBD12730G

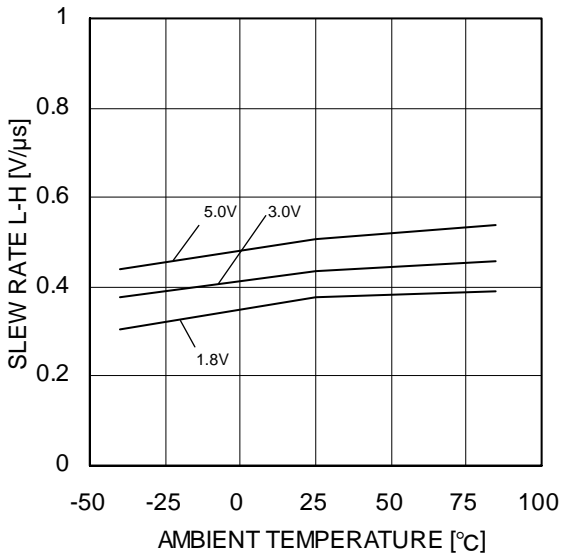


Figure 22.
 Slew Rate L-H - Ambient Temperature
 (RL=2kΩ)

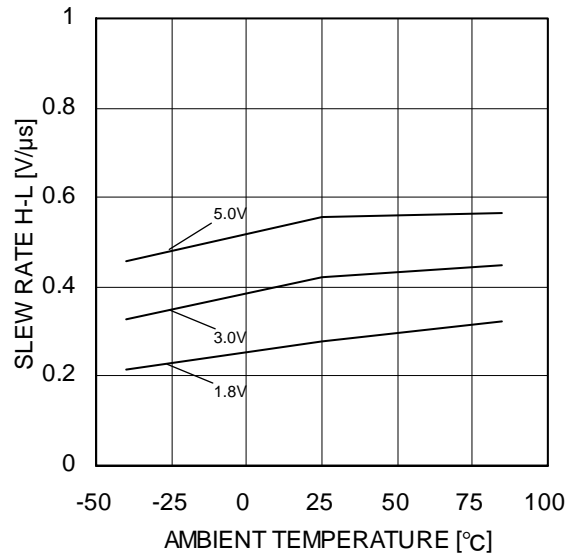


Figure 23.
 Slew Rate H-L - Ambient Temperature
 (RL=2kΩ)

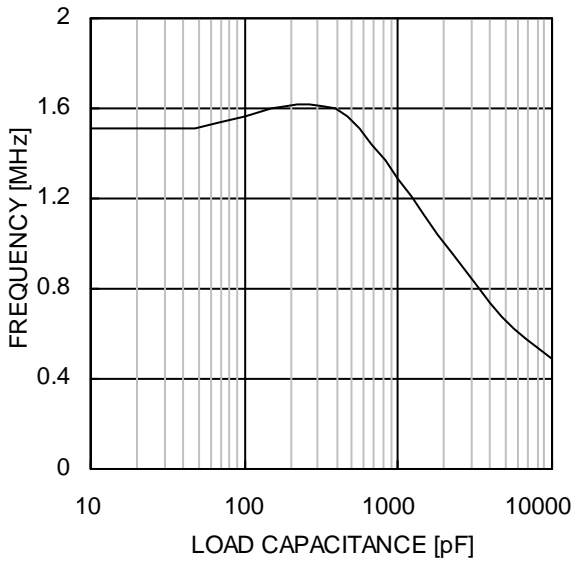


Figure 24.
 Unity Gain Bandwidth - Load Capacitance
 (V+=5V, Ta=25°C)

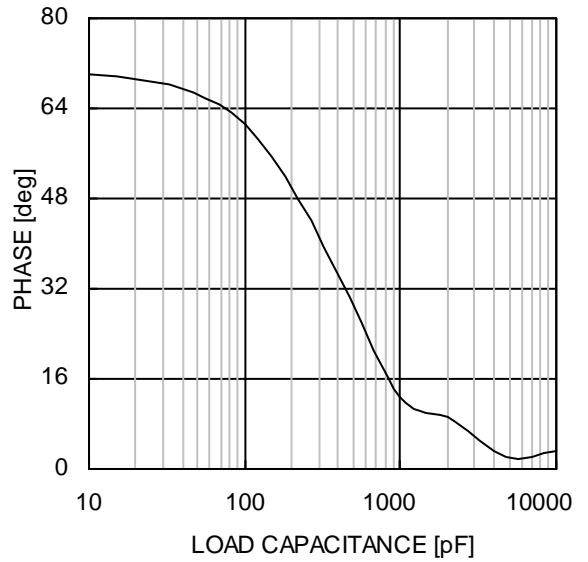


Figure 25.
 Phase Margin - Load Capacitance
 (V+=5V, Ta=25°C)

(*)The data above is measurement value of typical sample, it is not guaranteed.

● Typical Performance Curves (Reference data) – Continued
OBD12730G

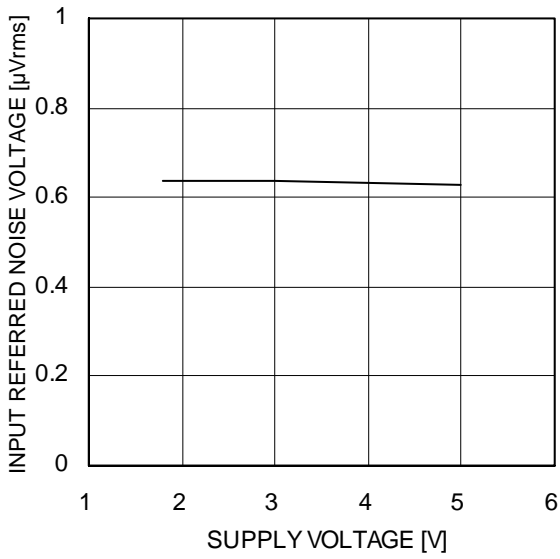


Figure 26.
Input Referred Noise Voltage - Supply Voltage
($T_a=25^\circ\text{C}$)

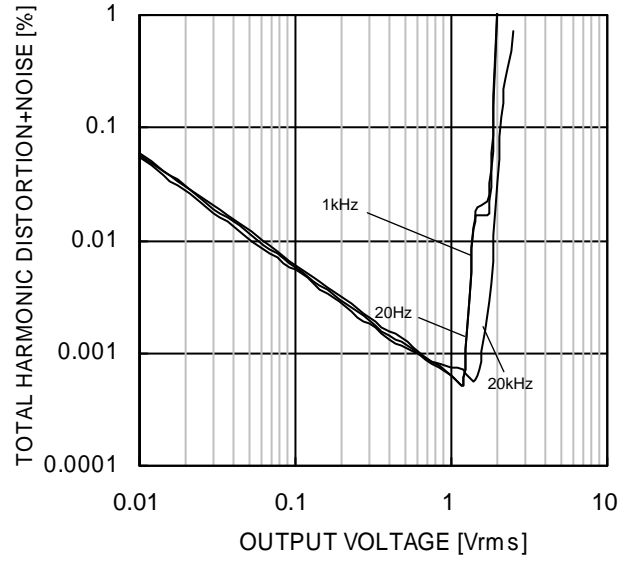


Figure 27.
Total Harmonic Distortion + Noise - Output Voltage
($V_+=5\text{V}$, $R_L=2\text{k}\Omega$, $T_a=25^\circ\text{C}$)

(*The data above is measurement value of typical sample, it is not guaranteed.

●Application Information

ONULL method condition for Test Circuit 1

V+, GND, VRL, EK, Vicm Unit: V

Parameter	VF	S1	S2	S3	V+	GND	VRL	RL Ω	EK	Vicm	Calculation
Input Offset Voltage	VF1	ON	ON	OFF	5.0	0	-	open	-2.5	2.5	1
Voltage Gain	VF2	ON	ON	ON	5.0	0	2.5	2k	-4.5	2.5	2
	VF3								-0.5		
Common Mode Rejection Ratio (Input Common-mode Voltage Range)	VF4	ON	ON	OFF	5.0	0	-	open	-2.5	0	3
	VF5								-2.5	5.0	
Supply Voltage Rejection Ratio	VF6	ON	ON	OFF	5.0	0	-	open	-2.5	2.5	4
	VF7				1.8						

— Calculation —

1. Input Offset Voltage (Vio)
$$V_{io} = \frac{|VF1|}{1+R_F/R_S} [V]$$

2. Large Signal Voltage Gain (Av)
$$A_v = 20\text{Log} \frac{\Delta E_K \times (1+R_F/R_S)}{|VF2-VF3|} [dB]$$

3. Common Mode Rejection Ratio (CMRR)
$$CMRR = 20\text{Log} \frac{\Delta V_{icm} \times (1+R_F/R_S)}{|VF4 - VF5|} [dB]$$

4. Supply Voltage Rejection Ratio (PSRR)
$$PSRR = 20\text{Log} \frac{\Delta V_+ \times (1+R_F/R_S)}{|VF6 - VF7|} [dB]$$

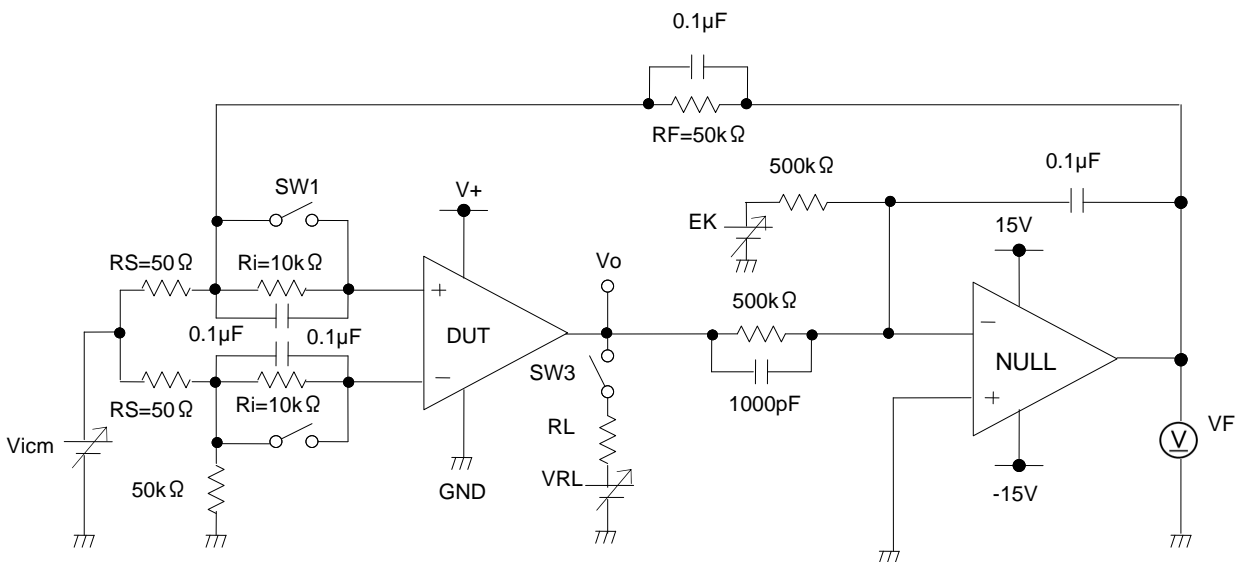


Figure 28. Test circuit 1

OSwitch Condition for Test Circuit 2

SW No.	SW1	SW2	SW3	SW4	SW5	SW6	SW7	SW8	SW9	SW10	SW11	SW12
Supply Current	OFF	OFF	ON	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Maximum Output Voltage	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF
Slew Rate	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	OFF	OFF	OFF	ON
Unity Gain Bandwidth	ON	OFF	OFF	ON	ON	OFF	OFF	ON	OFF	OFF	OFF	ON

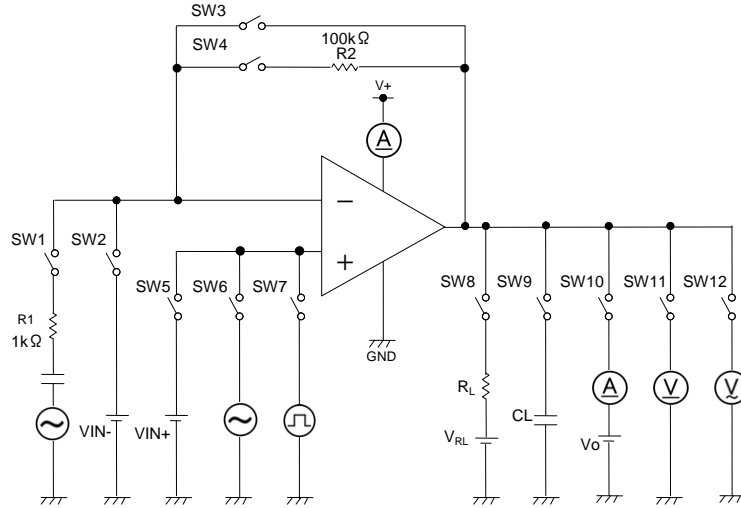


Figure 29. Test circuit2

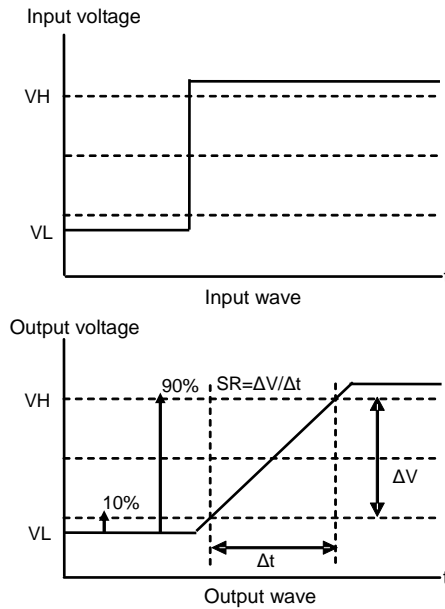


Figure 30. Slew rate input output wave

●Application example

○Voltage follower

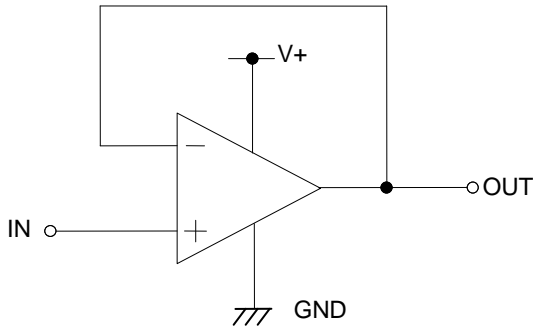


Figure 31. Voltage follower

Voltage gain is 0dB.

Using this circuit, the output voltage (OUT) is controlled to be equal to the input voltage (IN). This circuit also stabilizes OUT due to high input impedance and low output impedance. Computation for OUT is shown below.

$$OUT=IN$$

○Inverting amplifier

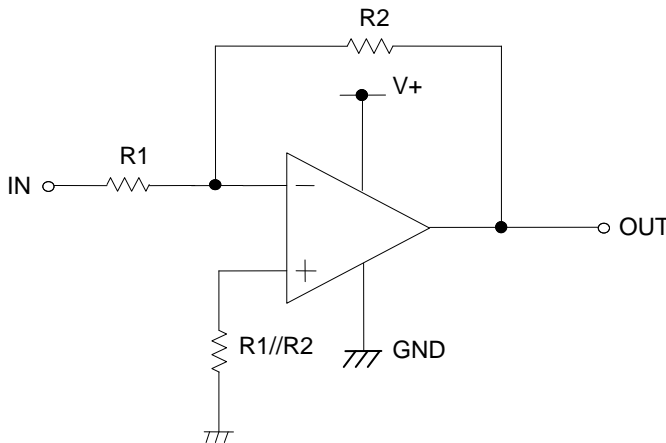


Figure 32. Inverting amplifier circuit

For inverting amplifier, IN is amplified by a voltage gain decided by the ratio of R1 and R2. The out-of-phase output voltage is shown in the next expression.

$$OUT=-\left(\frac{R2}{R1}\right) \cdot IN$$

This circuit has input impedance equal to R1.

○Non-inverting amplifier

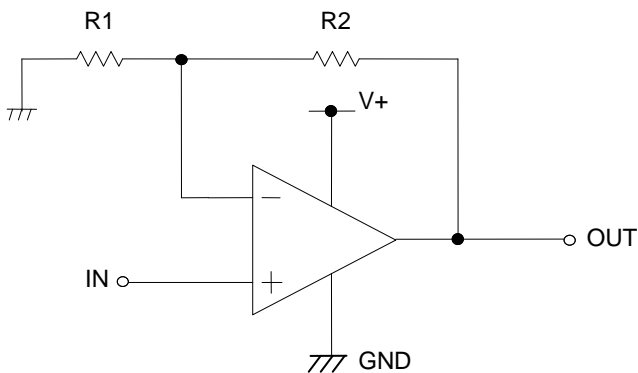


Figure 33. Non-inverting amplifier circuit

For non-inverting amplifier, IN is amplified by a voltage gain decided by the ratio of R1 and R2. OUT is in-phase with Vin and is shown in the next expression.

$$OUT=\left(1+\frac{R2}{R1}\right) \cdot IN$$

Effectively, this circuit has high input impedance since its input side is the same as that of the operational amplifier.

●Power Dissipation

Power dissipation (total loss) indicates the power that the IC can consume at Ta=25°C (normal temperature). As the IC consumes power, it heats up, causing its temperature to be higher than the ambient temperature. The allowable temperature that the IC can accept is limited. This depends on the circuit configuration, manufacturing process, and consumable power.

Power dissipation is determined by the allowable temperature within the IC (maximum junction temperature) and the thermal resistance of the package used (heat dissipation capability). Maximum junction temperature is typically equal to the maximum storage temperature. The heat generated through the consumption of power by the IC radiates from the mold resin or lead frame of the package. Thermal resistance, represented by the symbol θ_{ja} °C/W, indicates this heat dissipation capability. Similarly, the temperature of an IC inside its package can be estimated by thermal resistance.

Figure 34. (a) shows the model of the thermal resistance of a package. The equation below shows how to compute for the Thermal resistance (θ_{ja}), given the ambient temperature (Ta), maximum junction temperature (Tjmax), and power dissipation (Pd).

$$\theta_{ja} = (T_{jmax} - T_a) / P_d \quad \text{°C/W} \quad \dots \dots \dots (I)$$

The Derating curve in Figure 34. (b) indicates the power that the IC can consume with reference to ambient temperature. Power consumption of the IC begins to attenuate at certain temperatures. This gradient is determined by Thermal resistance (θ_{ja}), which depends on the chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc. This may also vary even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Figure 35 (c) shows an example of the derating curve for BD12730.

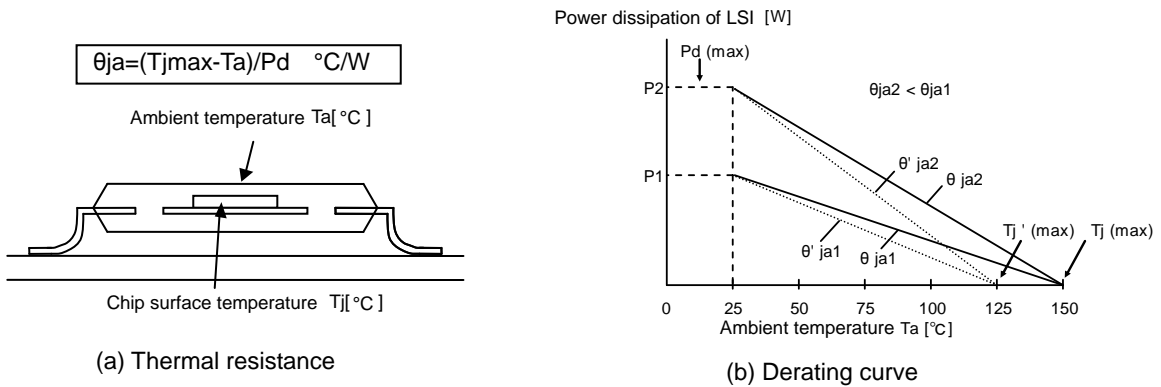
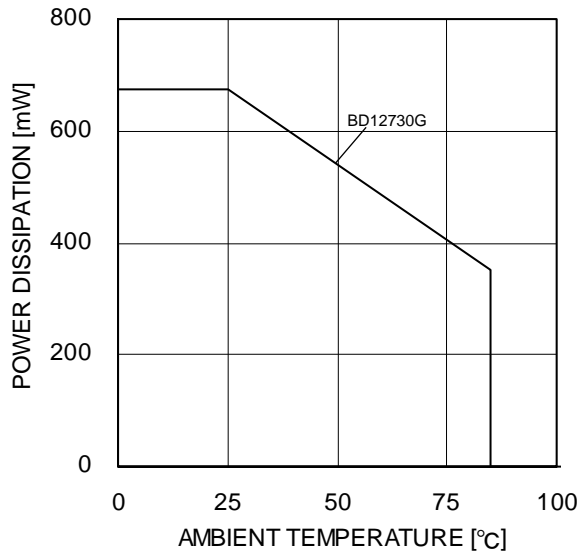


Figure 34. Thermal resistance and Derating Curve



(c) BD12730G

5.4	mW/°C
-----	-------

When using the unit above Ta=25°C, subtract the value above per degree°C. Permissible dissipation is the value when FR4 glass epoxy board 70mm × 70mm × 1.6mm (cooper foil area below 3%) is mounted

Figure 35. Derating Curve

●Operational Notes

- 1) Processing of unused circuit
It is recommended to apply the connection (see Figure 36.) and set the non-inverting input terminal at a potential within the Input Common-mode Voltage Range (Vicm) for any unused circuit.
- 2) Applied voltage to the input terminal
For normal circuit operation of voltage comparator, please input a voltage for its input terminal within Input Common-mode Voltage Range (Vicm). Then, regardless of power supply voltage, GND can be applied to input terminals without deterioration or destruction of its characteristics.
- 3) Operating power supply (split power supply/single power supply)
The voltage comparator operates if a certain level of voltage is applied between V+ and GND. Therefore, the operational amplifier can be operated under single power supply or split power supply.
- 4) Power dissipation (Pd)
If the IC is used under excessive power dissipation, an increase in the chip temperature will cause deterioration of the electrical characteristics of IC. As an example, reduction of current capability may happen. Take consideration of the effective power dissipation and thermal design with a sufficient margin. Pd is referenced to the provided power dissipation curve.
- 5) Short circuits between pins and incorrect mounting
When mounting the IC on a printed circuit board, take notice of the direction and position of the IC. If IC is mounted erroneously, it may be damaged. Also, when a foreign object is inserted between outputs, between output and V+ terminal, or between output and GND terminal, it causes short circuit which may damage the IC.
- 6) Usage under strong electromagnetic field
Be careful when using the IC under strong electromagnetic field because it may malfunction.
- 7) Usage of IC
When pressure is applied to the IC through warp on the printed circuit board, the characteristics may fluctuate due to the piezo effect. Be careful with the warp on the printed circuit board.
- 8) Testing IC on the application board
When testing IC on the application board, in cases where the capacitor is connected to low impedance, make sure to discharge per process because there is a possibility that the IC may be damaged due to stress. When removing IC from the application board, it is essential to cut the supply voltage. As a countermeasure against the static electricity, observe proper grounding during fabrication process and take due care when carrying and storing it.
- 9) The IC destruction caused by capacitive load
The IC may be damaged when V+ terminal and GND terminal is shorted with the charged output terminal capacitor. When IC is used as an operational amplifier or as an application circuit where oscillation is not activated by an output capacitor, output capacitor must be kept below 0.1 μ F in order to prevent the damage mentioned above.
- 10) Decoupling capacitor
Insert a decoupling capacitor between V+ and GND for stable operation of operational amplifier.

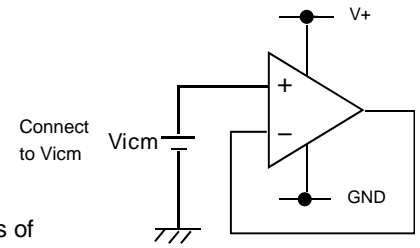


Figure 36.
Example of an application circuit for unused op-amp

Status of this document

The Japanese version of this document is the formal specification. A customer may use this translated version only for reference to help in reading the formal version.

If there are any differences in the translated version of this document, the formal version takes priority.

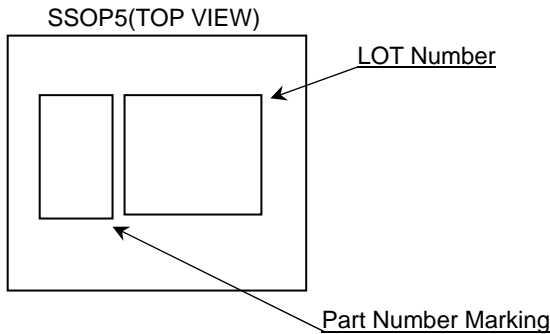
●Physical Dimensions Tape and Reel Information

SSOP5

Tape	Embossed carrier tape
Quantity	3000pcs
Direction of feed	TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)

* Order quantity needs to be multiple of the minimum quantity.

●Marking Diagram

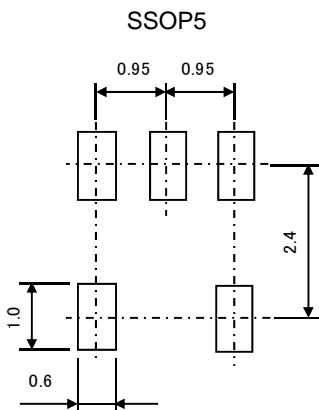


Product Name		Package Type	Marking
BD12730	G	SSOP5	K7

●Land pattern data

all dimensions in mm

PKG	Land pitch e	Land space MIE	Land length ≥ l 2	Land width b2
SSOP5	0.95	2.4	1.0	0.6



●Revision History

Date	Revision	Changes
30.NOV.2012	001	New Release

Notice

●General Precaution

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4) The Products are not subject to radiation-proof design.
- 5) Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6) In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse) is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7) De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8) Confirm that operation temperature is within the specified range described in the product specification.
- 9) ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

●Precaution for Mounting / Circuit board design

- 1) When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2) In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

●Precautions Regarding Application Examples and External Circuits

- 1) If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2) You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

●Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

●Precaution for Storage / Transportation

- 1) Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2) Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3) Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4) Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

●Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

●Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

●Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

●Precaution Regarding Intellectual Property Rights

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